



華泰電子股份有限公司

Orient Semiconductor Electronics ,Ltd.

(股票代號 : 2329)

2025年法人說明會
INVESTOR CONFERENCE

27 JUN ,2025

簡報大綱

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公司簡介



公司歷史



資本額 Capital : US\$ 247M(NTD7.40B)

Common Stock : US\$ 187M(NTD5.60B)

Preferred C Stock : US\$ 60M(NTD1.80B)

2025

54th Anniversary Celebration

2015 & 2020

Strategic Partnership Announcement

2014

1st 16D microSD in the world

2005

Biz Transformation into Memory Market

Apr, 1994

IPO in Taiwan Stock Exchange (TSE: 2329)

1971 Established

Founder : Dr. Eugene C. Y. Duh

Headquarters : Kaohsiung, Taiwan

公司生產據點



Headquarters (Flash Memory)
(750,000 sq. ft.)

- » 6 Production buildings in NTIP
- » Headcount : around 5,400



Facility 2
(59,223 sq. ft.)

LIC
(256,200 sq. ft.)



Facility 3
(158,638 sq. ft.)

Facility 1
(146,475 sq. ft.)



Facility 5
(190,000 sq. ft.)

公司組織

Chairman
Tony Tung

President
C. J. Tu

Testing Group

- Memory IC Testing Service
- Logic IC Testing Service

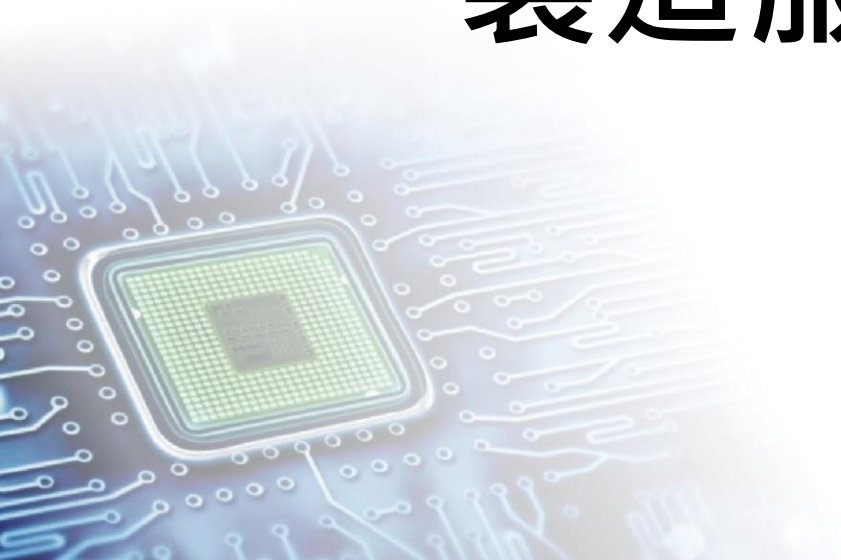
Semiconductor Group

- Memory IC Packaging Service
- Logic IC Packaging Service

EMS Group

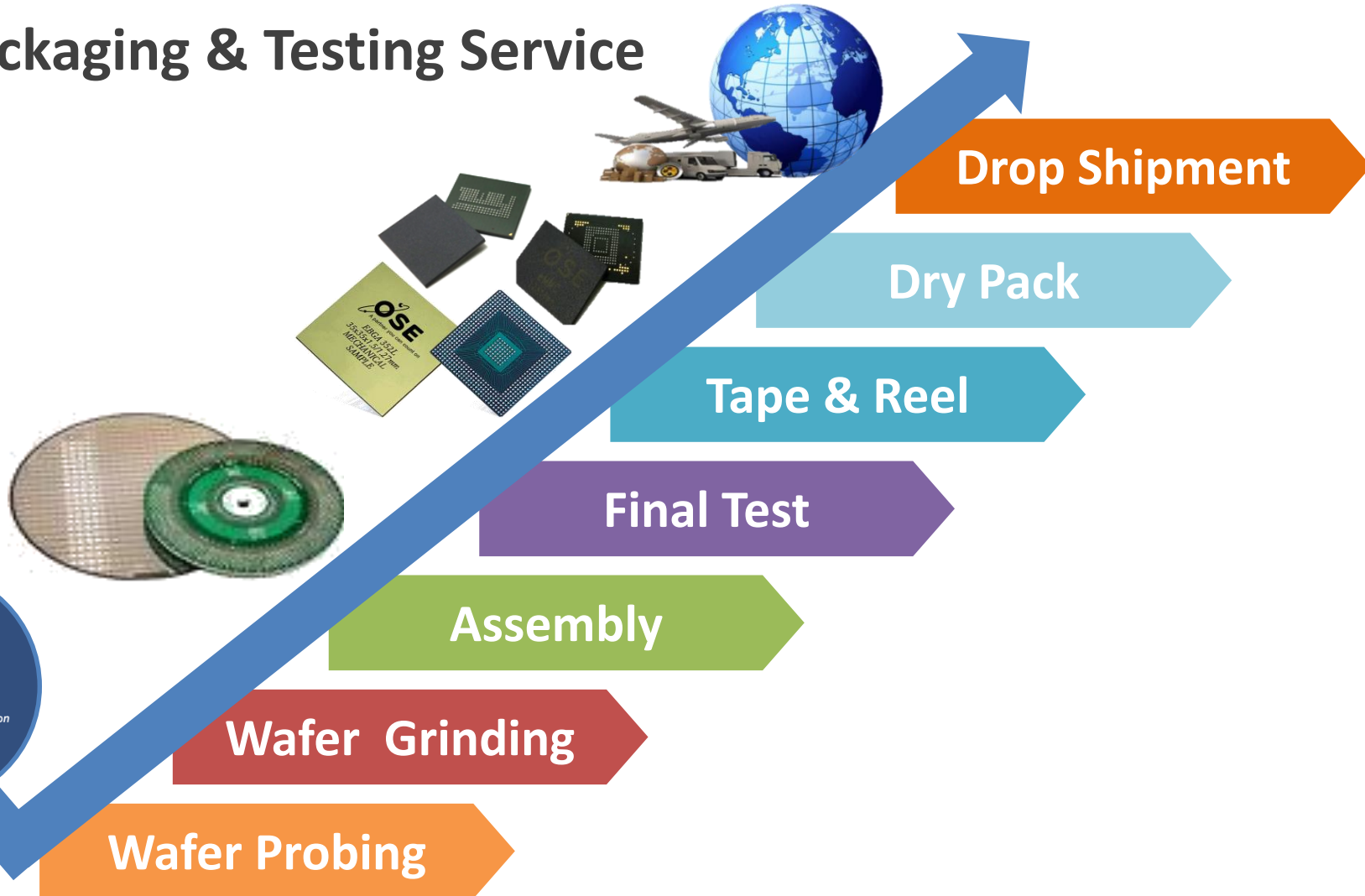
- EMS Service

製造服務及產品



IC生產流程

>> IC Packaging & Testing Service

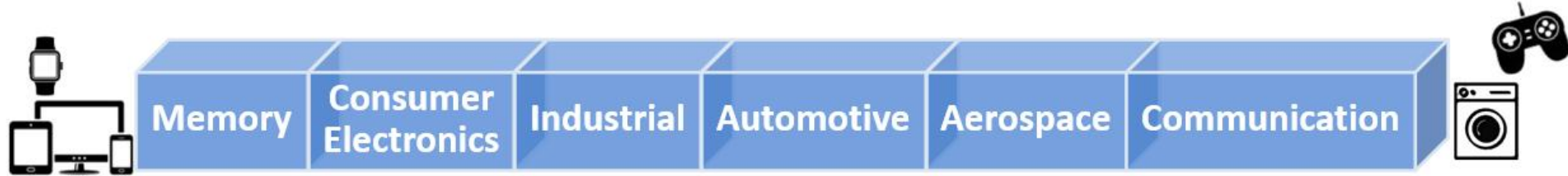


EMS生產流程

Electronics Manufacturing Service



產品及應用



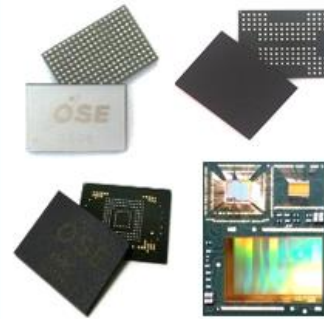
Leadframe



Flash Memory Card



CSP/SIP

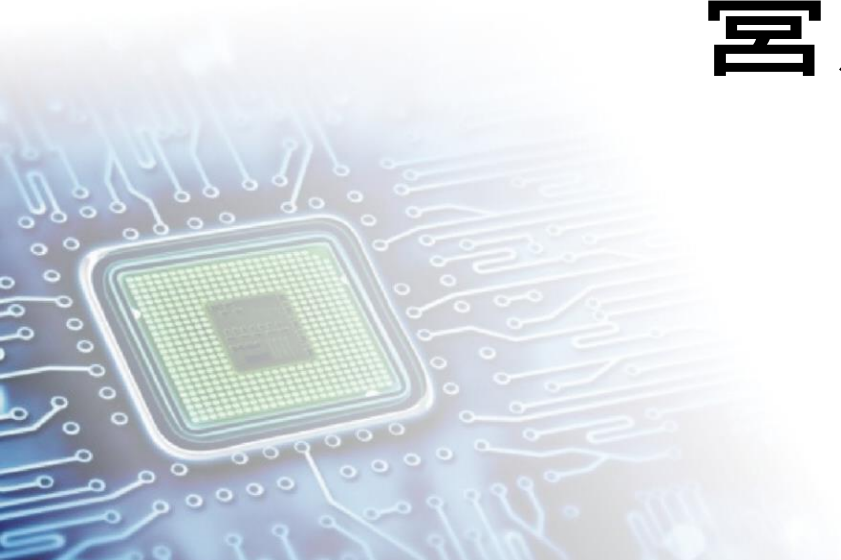


EMS



*Includes Wire Bond Type, Flip Chip Type, SiP, etc

2025 Q1 營運成果



合併綜合損益表(與上一季比較)

(單位：新台幣仟元)	Q1/2025	%	Q4/2024	%	季變化
營業收入淨額	4,077,476	100.00%	4,127,005	100.00%	(1.20%)
營業毛利	538,557	13.21%	562,517	13.63%	(4.26%)
營業淨利(淨損)	196,762	4.83%	191,798	4.65%	2.59%
稅前淨利(淨損)	231,357	5.67%	223,888	5.42%	3.34%
所得稅利益(費用)	(44,078)	(1.08%)	(25,508)	(0.62%)	72.80%
非控制權益	-	-	-	-	-
歸屬於本公司業主之淨利	187,279	4.59%	198,380	4.81%	(5.60%)
基本每股盈餘(新台幣元)	0.27	-	0.26	-	-
EBITDA	473,685	11.62%	457,394	11.08%	3.56%

合併綜合損益表(與去年同期比較)

(單位：新台幣仟元)	Q1/2025	%	Q1/2024	%	年變化
營業收入淨額	4,077,476	100.00%	4,176,029	100.00%	(2.36%)
營業毛利	538,557	13.21%	826,627	19.79%	(34.85%)
營業淨利(淨損)	196,762	4.83%	518,217	12.41%	(62.03%)
稅前淨利(淨損)	231,357	5.67%	622,033	14.90%	(62.81%)
所得稅利益(費用)	(44,078)	(1.08%)	(122,684)	(2.94%)	(64.07%)
非控制權益	-	-	-	-	-
歸屬於本公司業主之淨利	187,279	4.59%	499,349	11.96%	(62.50%)
基本每股盈餘(新台幣元)	0.27	-	0.7	-	(61.43%)
EBITDA	473,685	11.62%	843,720	20.20%	(43.86%)

重要資產負債表項目及財務指標(與上一季比較)

(單位：新台幣仟元)

	Q1/2025	Q4/2024	季變化
現金及約當現金	3,963,243	4,445,344	(10.85%)
按攤銷後成本衡量之金融資產	-	-	-
金融資產-非流動及採用權益法之投資	1,755,000	1,738,800	0.93%
不動產、廠房及設備	6,474,363	6,455,962	0.29%
資產總計	19,015,286	19,535,717	(2.66%)
短期借款及應付短期票券	-	-	-
一年或一營業週期內到期長期負債	418,997	372,122	12.60%
長期借款	928,705	1,009,786	(8.03%)
負債總計	7,937,407	7,965,664	(0.35%)
權益總計	11,077,879	11,570,053	(4.25%)
當季EBITDA	473,685	457,394	3.56%
重要財務指標			
負債比率	41.74%	40.77%	
應收帳款週轉天數(Q1)	90天	96天	
存貨週轉天數(Q1)	43天	41天	

重要資產負債表項目及財務指標(與去年同期比較)

(單位：新台幣仟元)

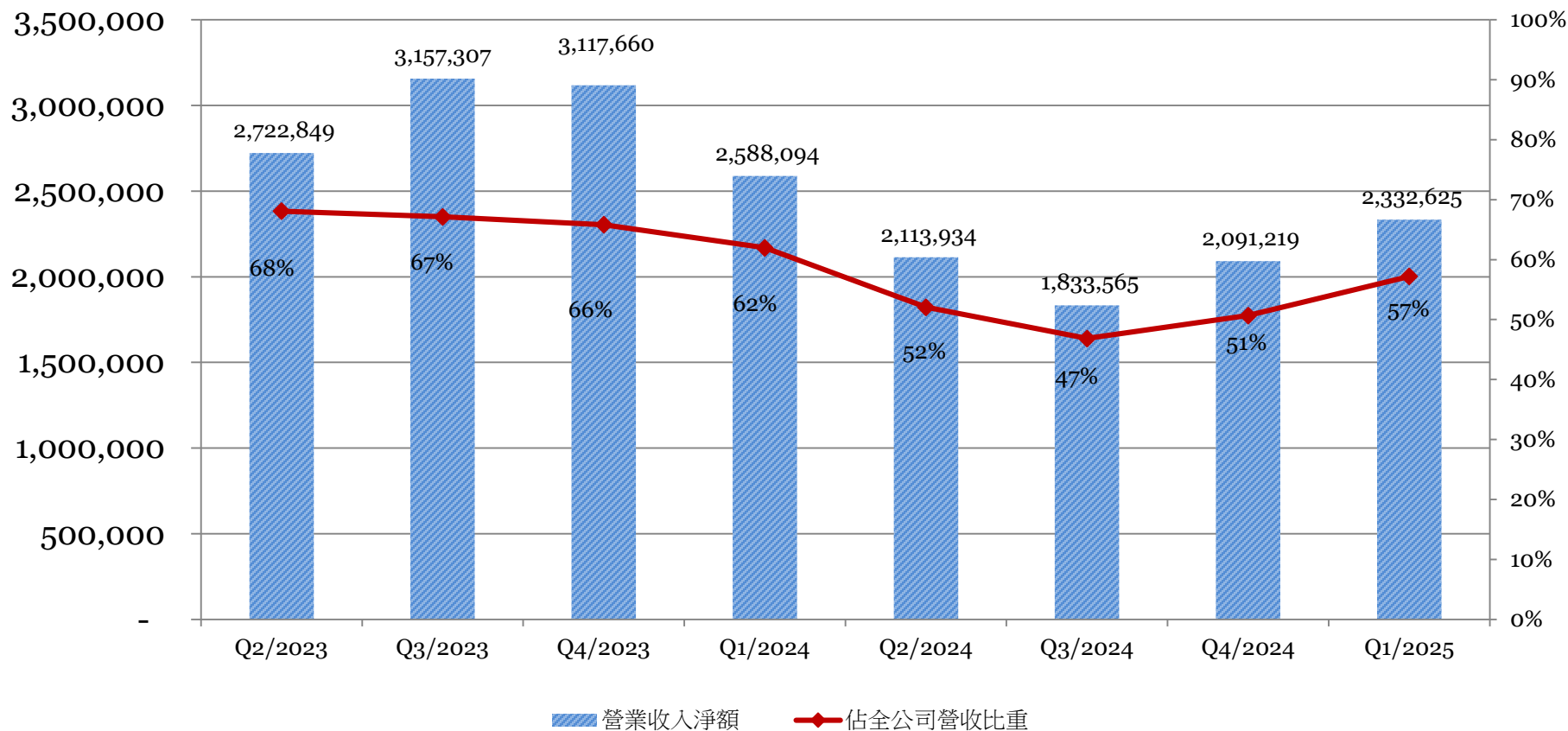
	Q1/2025	Q1/2024	年變化
現金及約當現金	3,963,243	4,281,821	(7.44%)
按攤銷後成本衡量之金融資產	-	-	-
金融資產-非流動及採用權益法之投資	1,755,000	2,055,652	(14.63%)
不動產、廠房及設備	6,474,363	5,370,723	20.55%
資產總計	19,015,286	19,259,288	(1.27%)
短期借款及應付短期票券	-	-	-
一年或一營業週期內到期長期負債	418,997	181,555	130.78%
長期借款	928,705	1,104,503	(15.92%)
負債總計	7,937,407	8,187,583	(3.06%)
權益總計	11,077,879	11,071,705	0.06%
當季EBITDA	473,685	843,720	(43.86%)

重要財務指標

負債比率	41.74%	42.51%
應收帳款週轉天數(Q1~Q1)	90 天	99 天
存貨週轉天數(Q1~Q1)	43 天	43天

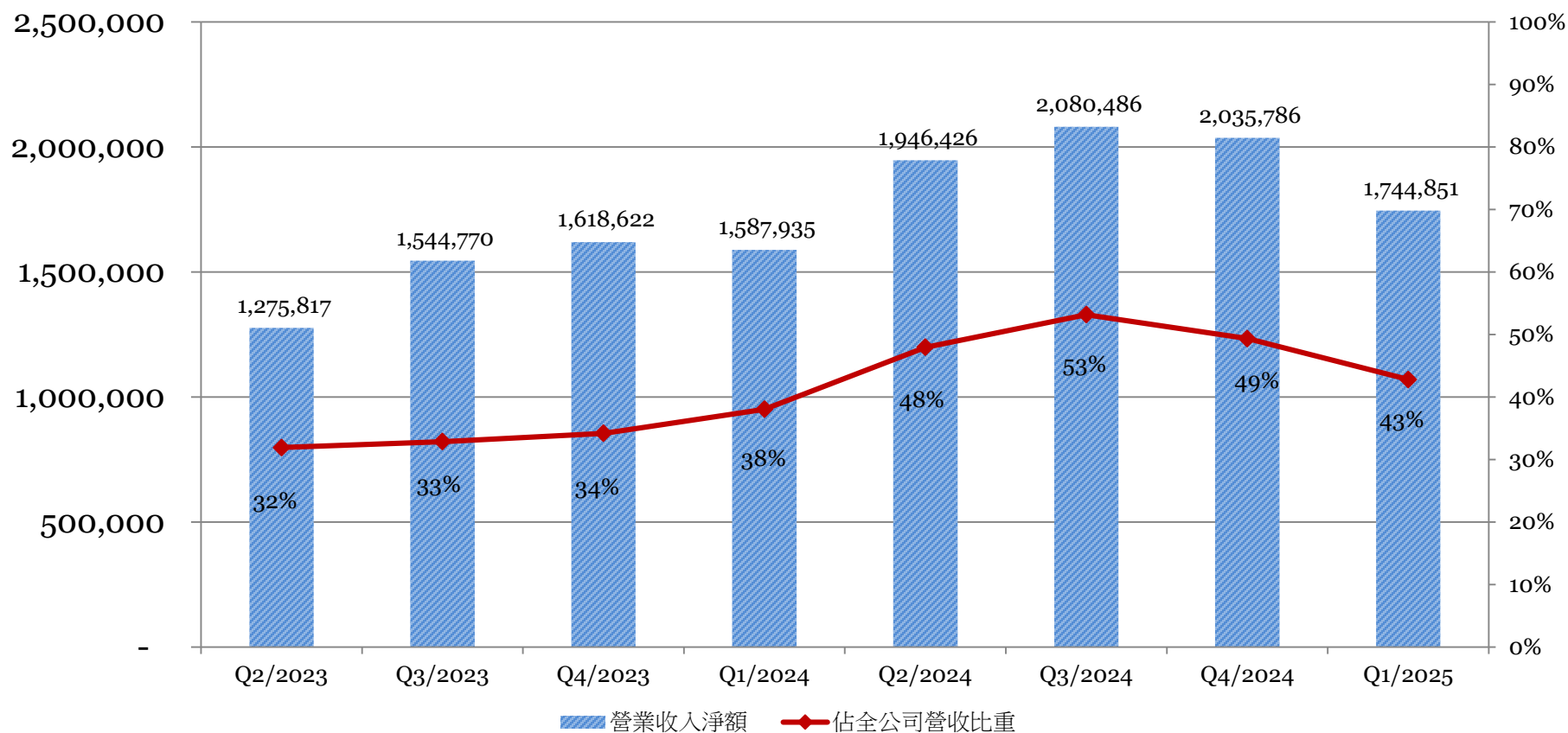
IC封測業務

(單位：新台幣仟元)

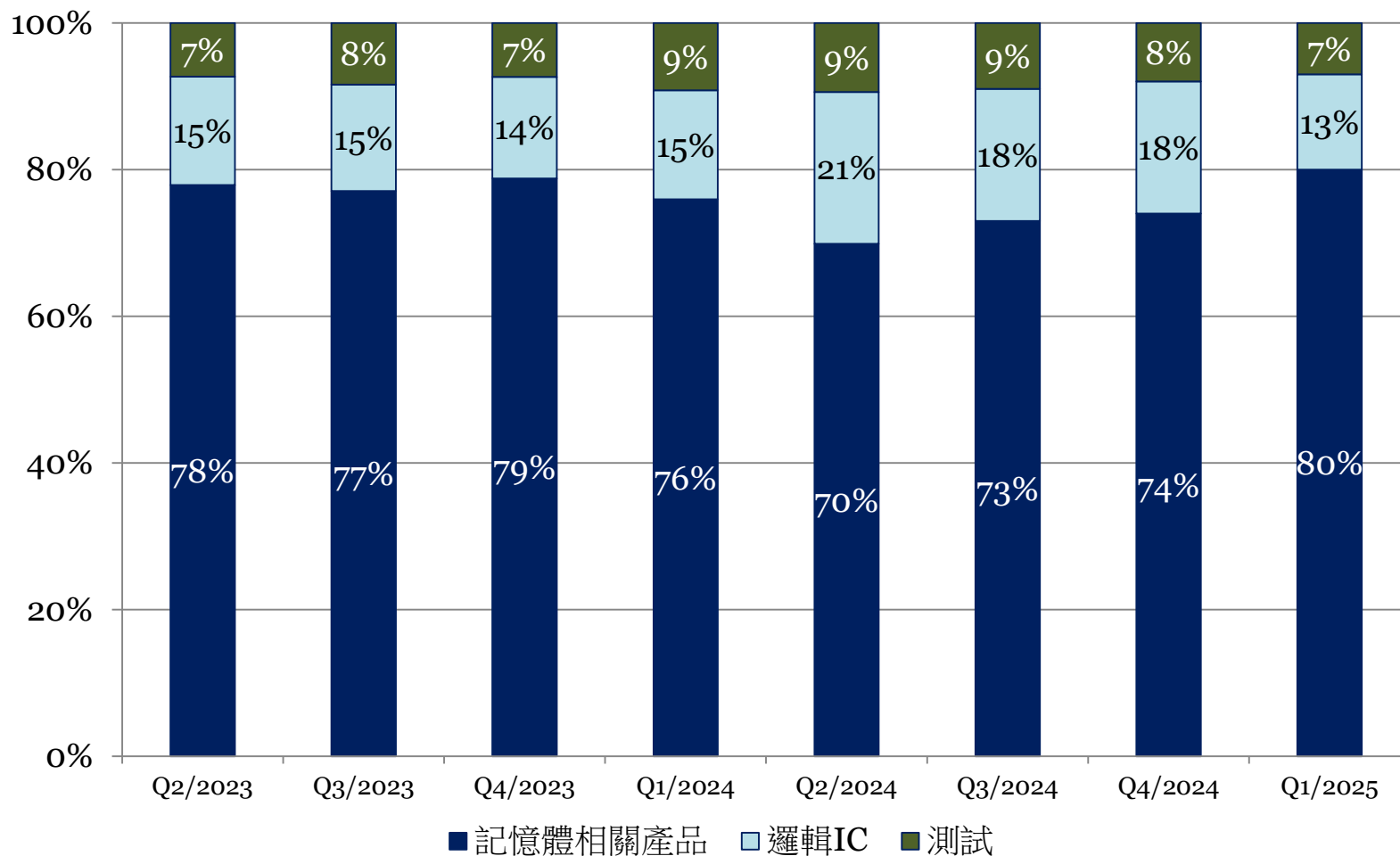


EMS業務

(單位：新台幣仟元)



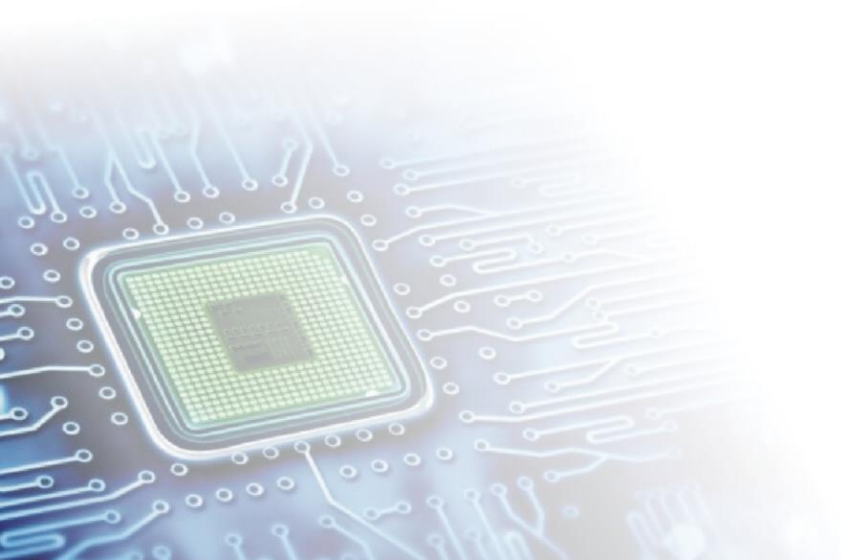
半導體封測營收-產品應用別佔比



2025 Q1~Q2 營運狀況 Summary

- 半導體事業中心
 - 記憶體在大廠減產效應，NAND 價格Q1來到谷底，客戶自三月開始啟動備貨
 - 川普關稅，加速客戶備貨機制
 - 半導體營收開始回昇，佔全公司比重上昇
 - IC產能利用率回昇
- EMS 事業中心
 - AI伺服器客戶需求強勁
 - 記憶體客戶啟動備貨，一條龍生產記憶體模組
 - 高產能利用率持續

競爭優勢



“WHAT OSE
COULD
OFFER”

“QUALITY
SPEED
FLEXIBILITY”



- Capable of both IC & EMS / One-Stop Service.
- Skilled experience with world-class customers working with us.



- **Advanced Process Capability**
 - 25um wafer thickness
 - 16 Layers Die Stacking for Micro SD/BGA/SD
 - Sip / Flip Chip / Wire Bond / Hybrid Availability
 - High-end Technology

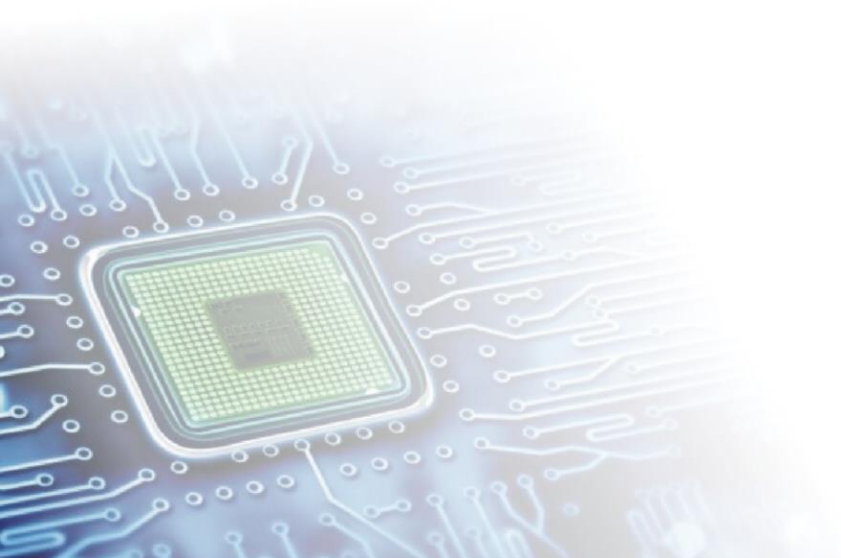


- Digitalization
- MES Automation System

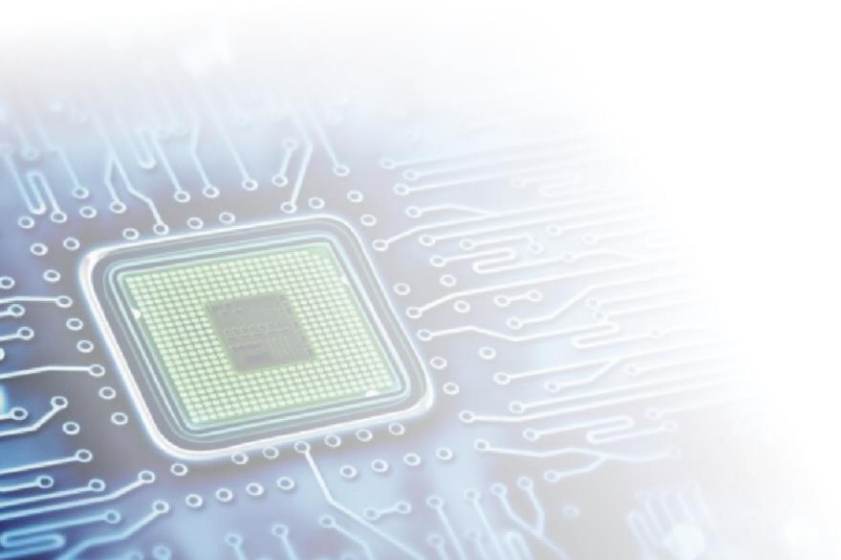


- Customer Oriented & Customization
- High Degree of Flexibility on capacity allocation

Q&A



感謝聆聽



聲明

The presentation and the relevant information mentioned in this material have been compiled from both internal and external resources.

These forward looking statements involve known and unknown risks, uncertainties and other factors, including price variation, competition, global economy, exchange rate movement and market demand, which may cause actual results to differ materially from those implied by such forward-looking statements.

The forward looking statements expressed in this material reflect the Company's current view about the future as of today. The Company is not responsible for any updates if there are any changes in the future.